

Title (en)

Thermally assisted flash memory with diode strapping

Title (de)

Thermisch gestützter Flash-Speicher mit Diodenkoppleitung

Title (fr)

Mémoire flash thermiquement assistée d'un cerclage de diode

Publication

**EP 2528061 B1 20150902 (EN)**

Application

**EP 12166199 A 20120430**

Priority

US 201113099298 A 20110502

Abstract (en)

[origin: EP2521135A1] A memory device (410) includes an array (412) of memory cells with charge trapping dielectric structures including word lines and bit lines. Control circuitry coupled to the array is arranged to control read, program and erase operations. A controller (434) is arranged with supporting circuitry to thermally anneal the charge trapping structures in the memory cells in the array. Word line drivers (25) and word line termination circuits (27) can be used to induce current flow on the word lines to induce heat for the annealing. The thermal annealing can be applied interleaved with normal operations for recover from cycling damage. Also, the thermally annealing can be applied during mission functions like erase, to improve performance of the function.

IPC 8 full level

**G11C 16/04** (2006.01); **G11C 16/34** (2006.01); **H01L 27/15** (2006.01); **H01L 29/792** (2006.01)

CPC (source: EP KR US)

**G11C 16/0416** (2013.01 - EP US); **G11C 16/0483** (2013.01 - EP US); **G11C 16/349** (2013.01 - EP US); **H01L 27/0814** (2013.01 - KR); **H01L 29/792** (2013.01 - EP US); **H10B 61/10** (2023.02 - KR); **H10B 63/20** (2023.02 - KR); **H10B 63/80** (2023.02 - KR)

Cited by

US9209172B2; US9263449B2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**EP 2521135 A1 20121107; EP 2521135 B1 20180502**; CN 102856326 A 20130102; CN 102856326 B 20150415; EP 2528061 A2 20121128; EP 2528061 A3 20131225; EP 2528061 B1 20150902; JP 2012238371 A 20121206; JP 2012238375 A 20121206; JP 6049297 B2 20161221; KR 101932465 B1 20190320; KR 102007271 B1 20190805; KR 20120124024 A 20121112; KR 20120124045 A 20121112; TW 201250693 A 20121216; TW I494928 B 20150801; US 2012281481 A1 20121108; US 8488387 B2 20130716

DOCDB simple family (application)

**EP 12163608 A 20120410**; CN 201210133486 A 20120502; EP 12166199 A 20120430; JP 2012088767 A 20120409; JP 2012104767 A 20120501; KR 20120039044 A 20120416; KR 20120046510 A 20120502; TW 101115558 A 20120502; US 201113099298 A 20110502